

B. AMENDMENTS TO THE CLAIMS

1. (currently amended) A semiconductor device, comprising:
a first resin package comprising:
a semiconductor chip;
a chip electrode on a surface of said semiconductor chip;
a first resin sealing said semiconductor chip; and
a first package electrode on a surface of said first resin; being electrically connected to said chip electrode, said first package electrode comprising a mounting pad
~~first electrode region connected to said chip electrode~~ and a testing pad provided apart
from said mounting pad and said testing pad being in contact with a testing probe to
enable electrical measurement of said semiconductor chip ~~second electrode region~~
~~connected to said first electrode region~~; and
a mounted object connected to said ~~first electrode region~~ mounting pad.
2. (currently amended) The semiconductor device as claimed in claim 1, further comprising:
a wiring connecting said ~~first electrode region~~ mounting pad to said mounted object.
3. (currently amended) The semiconductor device as claimed in claim 2, wherein
said ~~first electrode region~~ mounting pad is arranged along an edge of said first resin package, and

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wherein said ~~second electrode region~~testing pad is arranged at an inner position with respect to said ~~first electrode region~~mounting pad.

4. (original) The semiconductor device as claimed in claim 3, further comprising:
a second resin sealing said first resin package and a first surface of said mounted object.
5. (currently amended) The semiconductor device as claimed in claim 4, further comprising:
an inner wiring connecting said chip electrode to said ~~first electrode region~~mounting pad.
- 6-12. (withdrawn)
13. (original) The semiconductor device as claimed in claim 1, wherein said mounted object is a mounting substrate.
- 14-20. (withdrawn)